Preferred Device

# **Sensitive Gate Silicon Controlled Rectifiers**

# **Reverse Blocking Thyristors**

PNPN devices designed for high volume, low cost consumer applications such as temperature, light and speed control; process and remote control; and warning systems where reliability of operation is critical.

#### **Features**

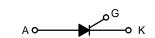
- Pb-Free Package is Available
- Small Size
- Passivated Die Surface for Reliability and Uniformity
- Low Level Triggering and Holding Characteristics
- Recommend Electrical Replacement for C106
- Surface Mount Package Case 369C
- To Obtain "DPAK" in Straight Lead Version (Shipped in Sleeves):
   Add '1' Suffix to Device Number, i.e., MCR706A1
- Epoxy Meets UL 94, V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V Machine Model, C > 400 V



## ON Semiconductor®

http://onsemi.com

# SCRs 4.0 AMPERES RMS 100 – 600 VOLTS



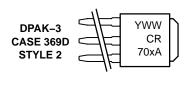
#### MARKING DIAGRAMS



DPAK CASE 369C STYLE 2







Y = Year WW = Work Week x = 3, 6, or 8

PIN ASSIGNMENT			
1	Gate		
2	Anode		
3	Cathode		
4	Anode		

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Rating  Peak Repetitive Off–State Voltage (Note 1)  (T <sub>C</sub> = -40 to +110°C, Sine Wave, 50 to 60 Hz, Gate Open)  MCR703A  MCR706A  MCR708A			Max	Unit	
			100 400 600	V	
Peak Non-Repetitive Off–State Voltage (Sine Wave, 50 to 60 Hz, Gate Open, $T_C = -40$ to +110°C)	MCR703A MCR706A MCR708A	V <sub>RSM</sub>	150 450 650	V	
On–State RMS Current (180° Conduction Angles; $T_C = 90$ °C)		I <sub>T(RMS)</sub>	4.0	Α	
Average On–State Current (180° Conduction Angles) $T_C = -40 \text{ to } +90^{\circ}\text{C}$ $T_C = +100^{\circ}\text{C}$		I <sub>T(AV)</sub>	2.6 1.6	А	
Non-Repetitive Surge Current (1/2 Sine Wave, 60 Hz, $T_J = 110^{\circ}\text{C}$ ) (1/2 Sine Wave, 1.5 ms, $T_J = 110^{\circ}\text{C}$ )		I <sub>TSM</sub>	25 35	А	
Circuit Fusing (t = 8.3 msec)		l <sup>2</sup> t	2.6	A <sup>2</sup> sec	
Forward Peak Gate Power (Pulse Width ≤ 1.0 μsec, T <sub>C</sub> = 90°C)		P <sub>GM</sub>	0.5	W	
Forward Average Gate Power (t = 8.3 msec, $T_C = 90^{\circ}C$ )		$P_{G(AV)}$	0.1	W	
Forward Peak Gate Current (Pulse Width $\leq$ 1.0 µsec, T <sub>C</sub> = 90°C)		I <sub>GM</sub>	0.2	Α	
Operating Junction Temperature Range		T <sub>J</sub>	-40 to +110	°C	
Storage Temperature Range		T <sub>stg</sub>	-40 to +150	°C	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	8.33	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	80	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

<sup>2.</sup> Case 369C when surface mounted on minimum pad sizes recommended.

V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

## **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Peak Repetitive Forward or Reverse Blocking Current ( $V_{AK}$ = Rated $V_{DRM}$ or $V_{RRM}$ ; $R_{GK}$ = 1 K $\Omega$ ) $T_{C}$ = 25°C $T_{C}$ = 110°C		I <sub>DRM</sub> , I <sub>RRM</sub>	- -	- -	10 200	μΑ
ON CHARACTERISTICS						
Peak Forward "On" Voltage (I <sub>TM</sub> = 8.2 A Peak, Pulse Width = 1 to 2 ms, 2% D	Outy Cycle)	V <sub>TM</sub>	_	_	2.2	V
Gate Trigger Current (Continuous dc) (Note 3) (V <sub>AK</sub> = 12 Vdc, R <sub>L</sub> = 24 Ohms)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	I <sub>GT</sub>	- -	25 -	75 300	μΑ
Gate Trigger Voltage (Continuous dc) (Note 3) (V <sub>AK</sub> = 12 Vdc, R <sub>L</sub> = 24 Ohms)	$T_C = 25$ °C $T_C = -40$ °C	V <sub>GT</sub>	- -	_ _	0.8 1.0	V
Gate Non-Trigger Voltage (Note 3) (V <sub>AK</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms, T <sub>C</sub> = 110°C)		$V_{GD}$	0.2	_	_	V
Holding Current (V <sub>AK</sub> = 12 Vdc, Gate Open) (Initiating Current = 200 mA)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	lн	- -	_ _	5.0 10	mA
Peak Reverse Gate Blocking Voltage (I <sub>GR</sub> = 10 μA)		$V_{RGM}$	10	12.5	18	V
Peak Reverse Gate Blocking Current (V <sub>GR</sub> = 10 V)		I <sub>RGM</sub>	-	_	1.2	μΑ
Total Turn-On Time (Source Voltage = 12 V, $R_S = 6 \text{ k}\Omega$ ) ( $I_{TM} = 8.2 \text{ A}$ , $I_{GT} = 2 \text{ mA}$ , Rated $V_{DRM}$ ) (Rise Time = 20 ns, Pulse Width = 10 $\mu$ s)		t <sub>gt</sub>	-	2.0	-	μs
DYNAMIC CHARACTERISTICS						
Critical Rate of Rise of Off–State Voltage $(V_D = Rated\ V_{DRM},\ R_{GK} = 1\ k\Omega,\ Exponential\ Wav T_C = 110°C)$	veform,	dv/dt	-	10	_	V/μs
Repetitive Critical Rate of Rise of On–State Current (Cf = 60 Hz, $I_{PK}$ = 30 A, PW = 100 $\mu$ s, diG/dt = 1		di/dt	-	-	100	A/μs

<sup>3.</sup> R<sub>GK</sub> current not included in measurement.

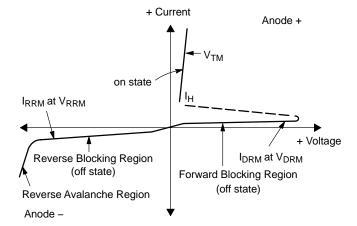
#### **ORDERING INFORMATION**

Device	Package Type	Package	Shipping <sup>†</sup>
MCR703AT4	DPAK	369C	2500 Tape & Reel
MCR706AT4	DPAK	369C	2500 Tape & Reel
MCR706AT4G	DPAK (Pb-Free)	369C	2500 Tape & Reel
MCR708A	DPAK	369C	2500 Tape & Reel
MCR708A1	DPAK-3	369D	75 Units / Rail
MCR708AT4	DPAK	369C	2500 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **Voltage Current Characteristic of SCR**

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Off-State Forward Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
V <sub>RRM</sub>	Peak Repetitive Off-State Reverse Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
$V_{TM}$	Peak On-State Voltage
IH	Holding Current



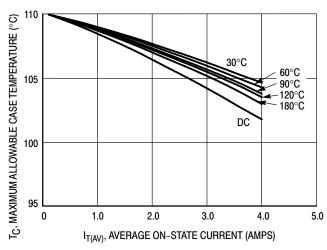


Figure 1. Average Current Derating

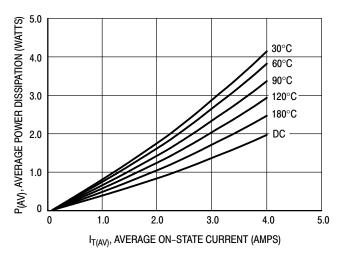


Figure 2. On-State Power Dissipation

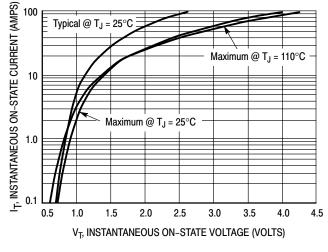
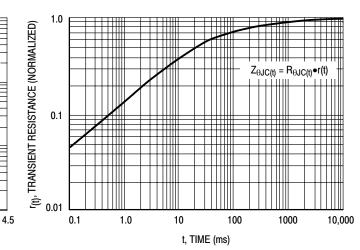


Figure 3. On-State Characteristics



**Figure 4. Transient Thermal Response** 

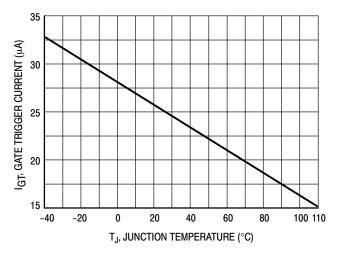


Figure 5. Typical Gate Trigger Current versus Junction Temperature

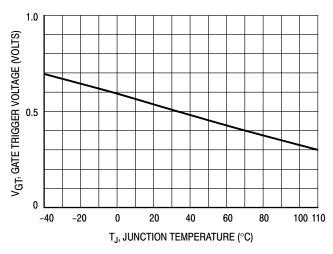


Figure 6. Typical Gate Trigger Voltage versus Junction Temperature

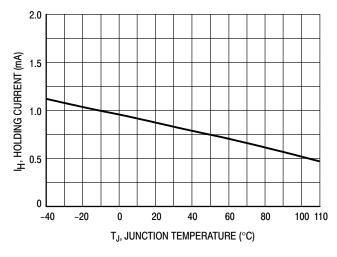


Figure 7. Typical Holding Current versus Junction Temperature

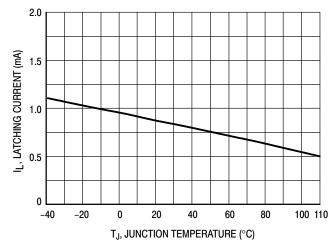
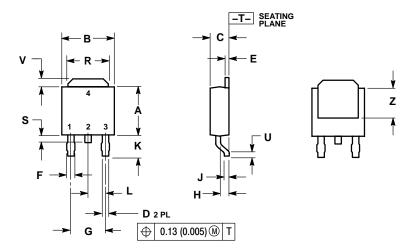


Figure 8. Typical Latching Current versus Junction Temperature

#### **PACKAGE DIMENSIONS**

#### **DPAK** CASE 369C **ISSUE O**

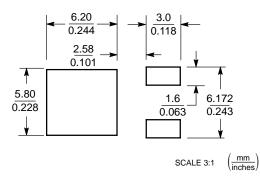


- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETER	
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.22
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180	BSC	4.58 BSC	
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090	BSC	2.29	BSC
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020		0.51	
٧	0.035	0.050	0.89	1.27
Z	0.155		3.93	

STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

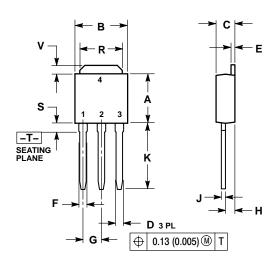
#### **SOLDERING FOOTPRINT\***

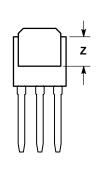


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **PACKAGE DIMENSIONS**

DPAK-3 CASE 369D-01 **ISSUE B** 





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETER	
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.35
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D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090	BSC	2.29 BSC	
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
٧	0.035	0.050	0.89	1.27
Z	0.155		3.93	

- STYLE 2:
  PIN 1. GATE
  2. DRAIN
  3. SOURCE
  4. DRAIN

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